

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>WEI-PIN HUANG</td> <td>01/20/2014</td> </tr> <tr> <td>WEN-CHI CHIEN</td> <td>01/20/2014</td> </tr> <tr> <td>BING-YUAN CHENG</td> <td>01/20/2014</td> </tr> <tr> <td>FENG-NING LEE</td> <td>01/20/2014</td> </tr> <tr> <td>WEI-CHENG WANG</td> <td>01/20/2014</td> </tr> </tbody> </table>		Name	Execution Date	WEI-PIN HUANG	01/20/2014	WEN-CHI CHIEN	01/20/2014	BING-YUAN CHENG	01/20/2014	FENG-NING LEE	01/20/2014	WEI-CHENG WANG	01/20/2014
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WEI-CHENG WANG	01/20/2014												
RECEIVING PARTY DATA													
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED												
Street Address:	NO. 8, LI-HSIN ROAD, VI												
Internal Address:	HSINCHU SCIENCE PARK												
City:	HSINCHU												
State/Country:	TAIWAN												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14157567</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14157567								
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Application Number:	14157567												
CORRESPONDENCE DATA													
Fax Number:	(212)755-7306												
Phone:	212-326-3939												
Email:	erosenfelder@JonesDay.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	JONES DAY												
Address Line 1:	222 EAST 41ST ST												
Address Line 4:	NEW YORK, NEW YORK 10017												
ATTORNEY DOCKET NUMBER:	181877-625057												
NAME OF SUBMITTER:	MATTHEW W. JOHNSON												

Signature:	/Matthew W. Johnson/
Date:	01/28/2014
Total Attachments: 2 source=625057_Assignment#page1.tif source=625057_Assignment#page2.tif	

JOINT

ASSIGNMENT

WHEREAS, WE, WEI-PIN HUANG, WEN-CHI CHIEN, BING-YUAN CHENG, FENG-NING LEE and WEI-CHENG WANG citizen of the Republic of China, having the mailing addresses listed as below.

WEI-PIN HUANG having a mailing address of No. 10, Neighborhood. 16, Liudong Vil, Toufen Township, Miaoli County 351, Taiwan residing at Miaoli County, Taiwan;

WEN-CHI CHIEN having a mailing address of No. 80, Dajhuang Village, Houlong Township, Miaoli County 356, Taiwan residing at Miaoli County, Taiwan;

BING-YUAN CHENG having a mailing address of 8F., No.42, Keda 1st Rd., Zhubei City, Hsinchu County 302, Taiwan residing at Hsinchu County, Taiwan;

FENG-NING LEE having a mailing address of No. 3, Alley 1, Lane 2, Xiangyun St., Longtan Shiang, Taoyuan County 325, Taiwan residing at Taoyuan County, Taiwan;

WEI-CHENG WANG having a mailing address of No. 115, Lane 47, Shuang-fu Rd., Neighbor 1, Guoling Village, Jongli City, Taoyuan County 320, Taiwan residing at Taoyuan County, Taiwan,

ASSIGNORS, are the inventors of the invention in "METHOD AND MANUFACTURING SYSTEM" for which we have executed an application for a Patent of the United States

- which is executed on even date herewith or
- which is identified by Jones Day docket no. 181877-625057
- which was filed on January _____, 2014, Application No. _____.
- We hereby authorize and request attorney(s) at Jones Day, to insert here in parentheses (Application number _____, filed _____) the filing date and application number of said application when known.

and WHEREAS, Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of Republic of China, and having an office for the transaction of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu, Taiwan, ASSIGNEE, is desirous of obtaining our entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said ASSIGNORS, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, our entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and all right to sue for infringement including past infringement.

AND WE HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, We hereunto set our hands and seals the day and year set opposite our respective signatures.

Date 01, 20, 2014

WEI-PIN HUANG L.S.
WEI-PIN HUANG

Date 1/20, 2014

wen-chi Chien L.S.
WEN-CHI CHIEN

Date 1/20, 2014

Bing-Yuan Cheng L.S.
BING-YUAN CHENG

Date 1/20, 2014

Feng-Ning Lee L.S.
FENG-NING LEE

Date 1/20, 2014

Wei-Cheng Wang L.S.
WEI-CHENG WANG